

# SEMI-THERM<sup>®</sup> 35

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**Keynote Speaker**  
Tuesday March 19, 2019 9:10a.m. – 10:10a.m.

## Challenges in the CPU and GPU Markets

The technical challenges for CPU and GPU products have gone through several inflections over the last 25 years. This talk will focus on these inflections as well as look forward to what may lie ahead.



### **Tom Dolbear, AMD**

Since October 2017, Tom has been the Senior Director in AMD's Radeon Technology Group leading the global board hardware engineering team responsible for electrical design, power regulation, and thermal/mechanical design for GPUs and graphics cards for the mobile, gaming, and datacenter/machine learning markets. From 2009 to October 2017, Tom directed AMD's global packaging organization, developing solutions for Playstation<sup>™</sup> 4 and Xbox<sup>™</sup> One, for Fiji and Vega GPUs utilizing 2.5D technology, and for the Epyc<sup>™</sup> and Ryzen<sup>™</sup> processors. Tom was the catalyst behind the integration of the AMD and ATI packaging teams in 2008. From 1995 to 2009, he worked in several architecture, packaging, and platform engineering roles within AMD, including being a key contributor to bringing Opteron<sup>™</sup> to the server market, the achievement of the first 1GHz CPU, and the development of AMD's first unique motherboard infrastructure for K7 CPUs.

Prior to joining AMD in 1995, he was a Member of Technical Staff at MCC, the first pre-competitive research

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